

Open consultation on Metrology for Semiconductor Technologies

Online event

8 July 2022 | 10:00 - 12:30 CEST

hosted by

EURAMET & the European Metrology Network for Advanced Manufacturing

Time CEST	Торіс	Speaker
10:00	Welcome & Introduction	Jörn Stenger, EURAMET Chairperson
10:05	The European Partnership on Metrology	Maguelonne Chambon, EURAMET Vice- Chairperson
10:15	The European Metrology Network (EMN) for Advanced Manufacturing	Harald Bosse, EMN Chair
10:25	The KDT Joint Undertaking. The European programme for RD&I in electronic components and systems.	Yves Gigase, Head of Programmes KDT JU
10:45	Metrology challenges for the semiconductor industry - An ASML Perspective	Wim Coene, ASML, Director of Research
11:00	Coffee break	
11:10	EUV-Lithography Optics: Challenges in Metrology	Kathrin Aziz-Lange, Carl Zeiss SMT, Head of Coating & Surface Roughness Metrology
11:25	Future CMOS and beyond-CMOS metrology needs	Paul van der Heide, IMEC, Director of MCA
11:40	Future needs related to Inline Metrology applied in Semiconductor Manufacturing	Delphine Le Cunff, STMicroelectronics, Deputy Head of PTC
11:55	Panel discussion: Opportunities for cooperation to support Europe's semiconductor ecosystem	
12:20	Wrap-up & closure of the event	Jörn Stenger, EURAMET Chairperson

The open consultation event will be chaired by EURAMET's General Secretary Mikko Merimaa.



Speakers

Dr Yves Gigase is the Head of Programmes of the Key Digital Technologies (KDT) Joint Undertaking (JU) and held the same position in the predecessors of KDT, the ECSEL JU and the ENIAC JU. He has a degree in Engineering physics, a PhD in opto-electronics. Yves background is in electronics, photonics and telecommunications, but also in nuclear physics and radioactive waste management. He has been working in various positions for companies in Belgium, Germany, Netherlands, Switzerland and the US. As Head of Programmes he manages the organisation of the calls, the selection of proposals, the monitoring of projects and more.

Dr Wim M. J. Coene received a PhD in physics from the University of Antwerp in 1986, for his research on computational modelling of image formation in a high-resolution transmission electron microscope (HR-TEM). He joined the Philips Research Laboratories in Eindhoven in 1988, where he worked on phase-retrieval methods in HR-TEM devised for digital correction of electron-optical aberrations. In 1996, he started to work on channel coding and signal processing for optical storage contributing to the Blu-Ray disc technology and beyond. Wim became a Fellow at Philips Research in 2001.

He joined ASML in 2007, where he is currently Director of Research. Since 2015, he is also parttime Professor at the Optics group of the Delft University of Technology. His scientific interests have focused on optical metrology for nanolithography in the semiconductor industry, directed to computational imaging, inverse problems and phase retrieval. In 2017 he has initiated and shaped a NWO-TTW Perspective Program with 5 academic groups in the Netherlands, on Lensless Imaging of 3D Nanostructures with Soft X-Rays (LINX).

Dr Kathrin Aziz-Lange is Head of Coating & Surface Roughness Metrology at Carl Zeiss SMT GmbH. Previously she was responsible for the development of optics manufacturing processes at Zeiss SMT, including predictive maintenance for the polishing machines. Prior to working at Zeiss Kathrin lead a Helmholtz Young Investigator Group where she developed methods for operando studies at the synchrotron light source BESSY II to study defects in advanced materials.

Dr Paul van der Heide is the director of the 'Materials and Component Analysis (MCA)' department at IMEC. MCA is responsible for the materials characterisation needs at IMEC and for exploring, developing and implementing the characterisation capabilities for tomorrow's semiconductor industry. Prior to moving to IMEC, Paul held positions at Globalfoundries, Samsung, and the University of Houston.

Dr Delphine Le Cunff has more than 20 years' experience in the field of metrology for semiconductor industry. After several years' experience as application scientist for a key optical metrology supplier, she joined STMicroelectronics in 2006 where she has worked with in-line metrology techniques covering the needs for advanced technology nodes to 3D integration. She is deeply involved in the field of innovation for new metrology solutions through collaborative projects with metrology suppliers and academics.